

Atty. Docket No. CPAC.1011-2

Appl. No. 10/081,425

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajendra PENDSE

Application No.: 10/081,425

Filed: February 22, 2002

Title: **Apparatus and process for precise
encapsulation of flip chip interconnects**

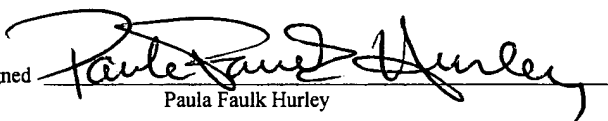
) Examiner: Scott B. GEYER

) Group Art Unit: 2829

) Date: February 23, 2004

) CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 23, 2004.

Signed 
Paula Faulk Hurley

COMMISSIONER FOR PATENTS
P.O. BOX 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

Applicant responds as follows to the Office action mailed September 23, 2003:

There are no amendments to the claims; the claims as presented in the RCE as filed on August 7, 2003, are reflected in the **Listing of Claims** which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.